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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	16MHz
Connectivity	I <sup>2</sup> C
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	5
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	D/A 1x7b, 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-SOIC (0.154", 3.90mm Width)
Supplier Device Package	8-SOIC
Purchase URL	<a href="https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4013sxi-410t">https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4013sxi-410t</a>

## More Information

Cypress provides a wealth of data at [www.cypress.com](http://www.cypress.com) to help you to select the right PSoC device for your design, and to help you to quickly and effectively integrate the device into your design. For a comprehensive list of resources, see the knowledge base article [KBA86521, How to Design with PSoC 3, PSoC 4, and PSoC 5LP](#). Following is an abbreviated list for PSoC 4:

- Overview: [PSoC Portfolio](#), [PSoC Roadmap](#)
- Product Selectors: [PSoC 1](#), [PSoC 3](#), [PSoC 4](#), [PSoC 5LP](#)  
In addition, PSoC Creator includes a device selection tool.
- Application notes: Cypress offers a large number of PSoC application notes covering a broad range of topics, from basic to advanced level. Recommended application notes for getting started with PSoC 4 are:
  - [AN79953](#): Getting Started With PSoC 4
  - [AN88619](#): PSoC 4 Hardware Design Considerations
  - [AN86439](#): Using PSoC 4 GPIO Pins
  - [AN57821](#): Mixed Signal Circuit Board Layout
  - [AN81623](#): Digital Design Best Practices
  - [AN73854](#): Introduction To Bootloaders
  - [AN89610](#): ARM Cortex Code Optimization
- Technical Reference Manual (TRM) is in two documents:
  - [Architecture TRM](#) details each PSoC 4 functional block.
  - [Registers TRM](#) describes each of the PSoC 4 registers.
- Development Kits:
  - CY8CKIT-040, PSoC 4000 Pioneer Kit, is an easy-to-use and inexpensive development platform with debugging capability. This kit includes connectors for Arduino<sup>™</sup> compatible shields and Digilent<sup>®</sup> Pmod<sup>™</sup> daughter cards.
  - The MiniProg3 device provides an interface for flash programming and debug.

## PSoC Creator

[PSoC Creator](#) is a free Windows-based Integrated Design Environment (IDE). It enables concurrent hardware and firmware design of PSoC 3, PSoC 4, and PSoC 5LP based systems. Create designs using classic, familiar schematic capture supported by over 100 pre-verified, production-ready PSoC Components; see the [list of component datasheets](#). With PSoC Creator, you can:

1. Drag and drop component icons to build your hardware system design in the main design workspace
2. Codesign your application firmware with the PSoC hardware, using the PSoC Creator IDE C compiler
3. Configure components using the configuration tools
4. Explore the library of 100+ components
5. Review component datasheets

Figure 1. CapSense Example Project in PSoC Creator

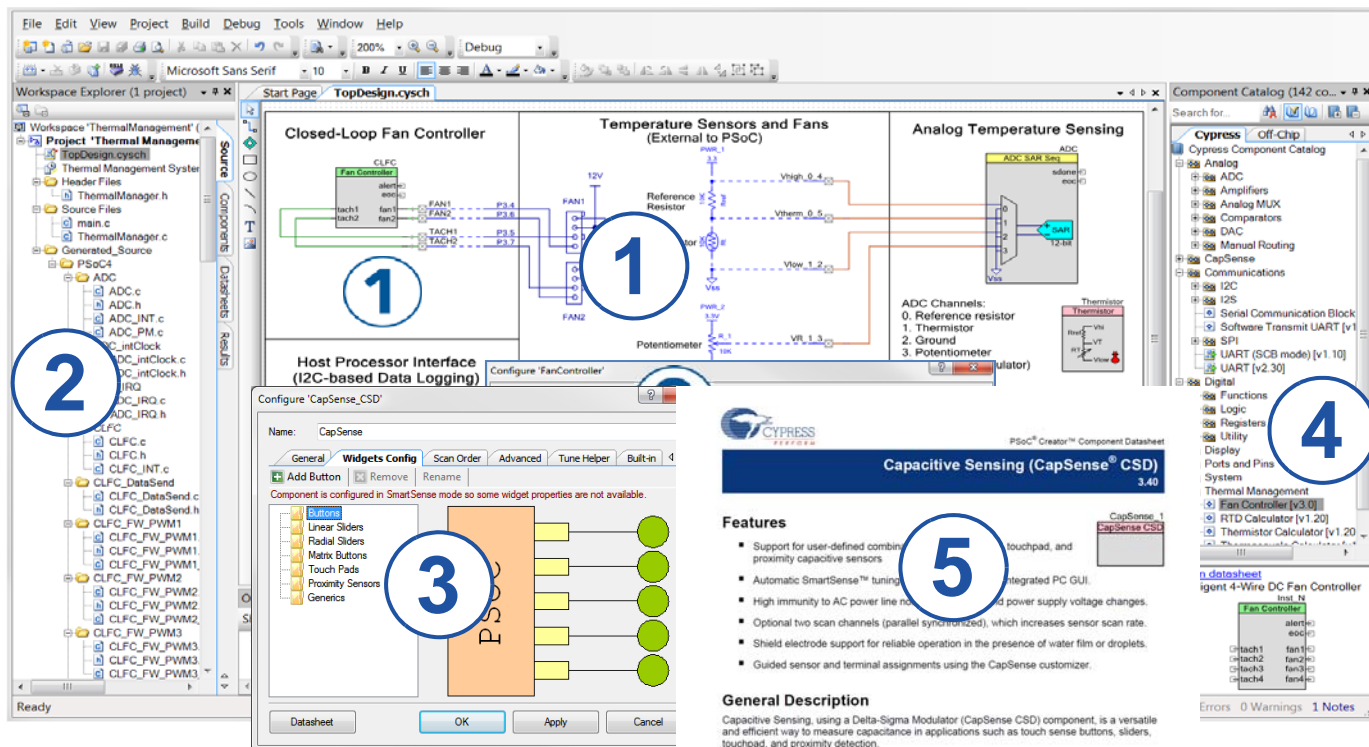
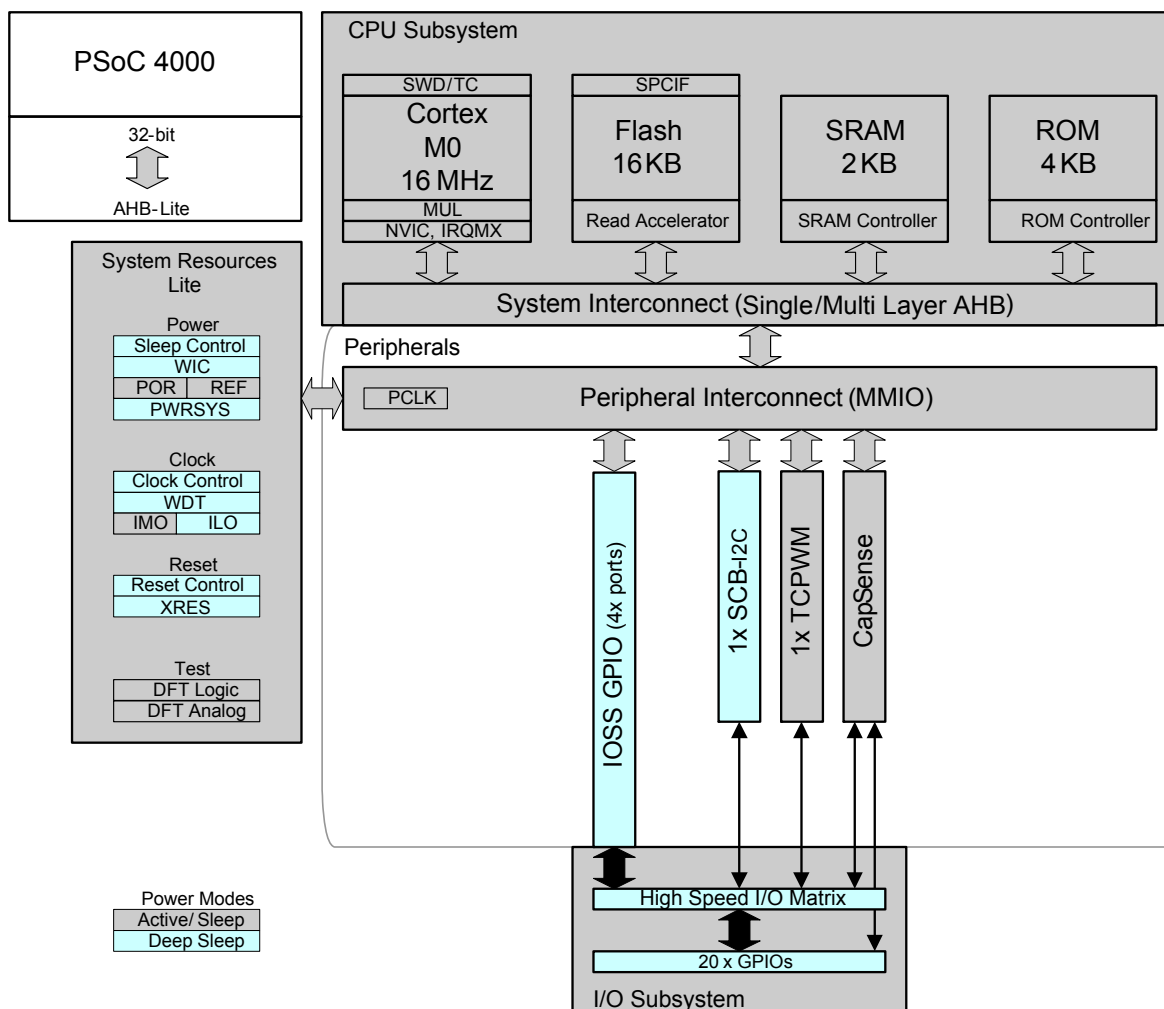


Figure 2. Block Diagram



PSoC 4000 devices include extensive support for programming, testing, debugging, and tracing both hardware and firmware.

The ARM Serial-Wire Debug (SWD) interface supports all programming and debug features of the device.

Complete debug-on-chip functionality enables full-device debugging in the final system using the standard production device. It does not require special interfaces, debugging pods, simulators, or emulators. Only the standard programming connections are required to fully support debug.

The PSoC Creator IDE provides fully integrated programming and debug support for the PSoC 4000 devices. The SWD interface is fully compatible with industry-standard third-party tools. The PSoC 4000 family provides a level of security not possible with multi-chip application solutions or with microcontrollers. It has the following advantages:

- Allows disabling of debug features
- Robust flash protection
- Allows customer-proprietary functionality to be implemented in on-chip programmable blocks

The debug circuits are enabled by default and can only be disabled in firmware. If they are not enabled, the only way to re-enable them is to erase the entire device, clear flash protection, and reprogram the device with new firmware that enables debugging.

Additionally, all device interfaces can be permanently disabled (device security) for applications concerned about phishing attacks due to a maliciously reprogrammed device or attempts to defeat security by starting and interrupting flash programming sequences. All programming, debug, and test interfaces are disabled when maximum device security is enabled. Therefore, PSoC 4000, with device security enabled, may not be returned for failure analysis. This is a trade-off the PSoC 4000 allows the customer to make.

## Pinouts

All port pins support GPIO. Ports 0, 1, and 2 support CSD CapSense and analog multiplexed bus connections. TCPWM functions and Alternate Functions are multiplexed with port pins as follows for the five PSoC 4000 packages.

**Table 1. Pin Descriptions**

28-Pin SSOP		24-Pin QFN		16-Pin QFN		16-Pin SOIC		8-Pin SOIC		TCPWM Signals	Alternate Functions
Pin	Name	Pin	Name	Pin	Name	Pin	Name	Pin	Name		
20	VSS										
21	P0.0/TRIN0	1	P0.0/TRIN0							TRIN0: Trigger Input 0	
22	P0.1/TRIN1/CMPO_0	2	P0.1/TRIN1/CMPO_0	1	P0.1/TRIN1/CMPO_0	3	P0.1/TRIN1/CMPO_0			TRIN1: Trigger Input 1	CMPO_0: Sense Comp Out
23	P0.2/TRIN2	3	P0.2/TRIN2	2	P0.2/TRIN2	4	P0.2/TRIN2			TRIN2: Trigger Input 2	
24	P0.3/TRIN3	4	P0.3/TRIN3							TRIN3: Trigger Input 3	
25	P0.4/TRIN4/CMPO_0/EXT_CLK	5	P0.4/TRIN4/CMPO_0/EXT_CLK	3	P0.4/TRIN4/CMPO_0/EXT_CLK	5	P0.4/TRIN4/CMPO_0/EXT_CLK	2	P0.4/TRIN4/CMPO_0/EXT_CLK	TRIN4: Trigger Input 4	CMPO_0: Sense Comp Out, External Clock, CMOD Cap
26	VCC	6	VCC	4	VCC	6	VCC	3	VCC		
27	VDD	7	VDD	6	VDD	7	VDD	4	VDD		
28	VSS	8	VSS	7	VSS	8	VSS	5	VSS		
1	P0.5	9	P0.5	5	VDDIO	9	P0.5				
2	P0.6	10	P0.6	8	P0.6	10	P0.6				
3	P0.7	11	P0.7								
4	P1.0	12	P1.0								
5	P1.1/OUT0	13	P1.1/OUT0	9	P1.1/OUT0	11	P1.1/OUT0	6	P1.1/OUT0	OUT0: PWM OUT 0	
6	P1.2/SCL	14	P1.2/SCL	10	P1.2/SCL	12	P1.2/SCL				I2C Clock
7	P1.3/SDA	15	P1.3/SDA	11	P1.3/SDA	13	P1.3/SDA				I2C Data
8	P1.4/UND0	16	P1.4/UND0							UND0: Underflow Out	
9	P1.5/OVF0	17	P1.5/OVF0							OVF0: Overflow Out	
10	P1.6/OVF0/UND0/nOUT0/CMPO_0	18	P1.6/OVF0/UND0/nOUT0/CMPO_0	12	P1.6/OVF0/UND0/nOUT0/CMPO_0	14	P1.6/OVF0/UND0/nOUT0/CMPO_0	7	P1.6/OVF0/UND0/nOUT0/CMPO_0	nOUT0: Complement of OUT0, UND0, OVF0 as above	CMPO_0: Sense Comp Out, Internal Reset function <sup>[1]</sup>

**Note**

1. Must not have load to ground during POR (should be an output).

**Table 1. Pin Descriptions** *(continued)*

28-Pin SSOP		24-Pin QFN		16-Pin QFN		16-Pin SOIC		8-Pin SOIC		TCPWM Signals	Alternate Functions
Pin	Name	Pin	Name	Pin	Name	Pin	Name	Pin	Name		
11	VSS										
12	No Connect (NC) <sup>[2]</sup>										
13	P1.7/MATCH/EXT_CLK	19	P1.7/MATCH/EXT_CLK	13	P1.7/MATCH/EXT_CLK	15	P1.7/MATCH/EXT_CLK			MATCH: Match Out	External Clock
14	P2.0	20	P2.0			16	P2.0				
15	VSS										
16	P3.0/SDA/SWD_IO	21	P3.0/SDA/SWD_IO	14	P3.0/SDA/SWD_IO	1	P3.0/SDA/SWD_IO	8	P3.0/SDA/SWD_IO		I2C Data, SWD I/O
17	P3.1/SCL/SWD_CLK	22	P3.1/SCL/SWD_CLK	15	P3.1/SCL/SWD_CLK	2	P3.1/SCL/SWD_CLK	1	P3.1/SCL/SWD_CLK		I2C Clock, SWD Clock
18	P3.2	23	P3.2	16	P3.2					OUT0:PWM OUT 0	
19	XRES	24	XRES								XRES: External Reset

**Descriptions of the Pin functions are as follows:**

**VDD:** Power supply for both analog and digital sections.

**VDDIO:** Where available, this pin provides a separate voltage domain (see the [Power](#) section for details).

**VSS:** Ground pin.

**VCCD:** Regulated digital supply (1.8 V ±5%).

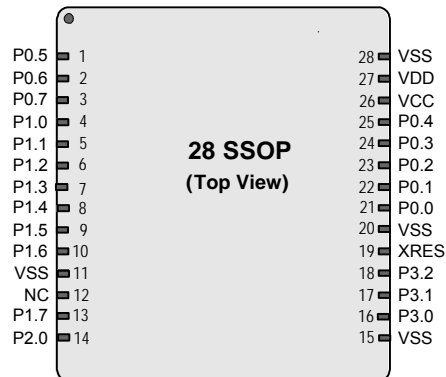
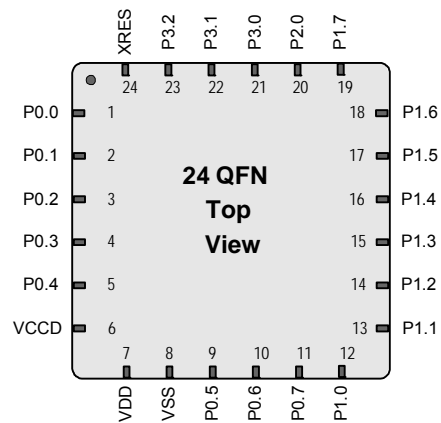
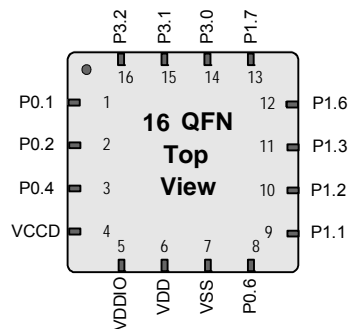
Pins belonging to Ports 0, 1, and 2 can all be used as CSD sense or shield pins connected to AMUXBUS A or B. They can also be used as GPIO pins that can be driven by the firmware, in addition to their alternate functions listed in the [Table 1](#).

Pins on Port 3 can be used as GPIO, in addition to their alternate functions listed above.

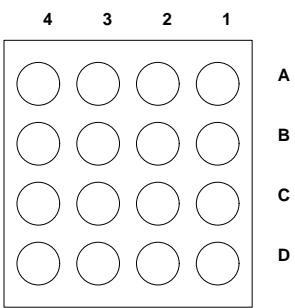
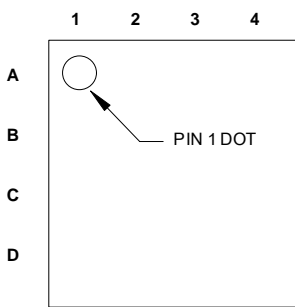
The following packages are provided: 28-pin SSOP, 24-pin QFN, 16-pin QFN, 16-pin SOIC, and 8-pin SOIC.

**Note**

2. This pin is not to be used; it must be left floating.

**Figure 4. 28-Pin SSOP Pinout**

**Figure 5. 24-pin QFN Pinout**

**Figure 6. 16-Pin QFN Pinout**


**Table 2. 16-ball WLCSP Pin Descriptions and Diagram**

Pin	Name	TCPWM Signal	Alternate Functions	Pin Diagram
B4	P3.2	OUT0:PWMOUT0	—	<p>Bottom View</p>  <p>Top View</p> 
C3	P0.2/TRIN2	TRIN2:Trigger Input 2	—	
C4	P0.4/TRIN4/CMPO_0/ EXT_CLK	TRIN4:Trigger Input 4	CMPO_0: Sense Comp Out, Ext. Clock, CMOD Cap	
D4	VCCD	—	—	
D3	VDD	—	—	
D2	VSS	—	—	
C2	VDDIO	—	—	
D1	P0.6	—	—	
C1	P1.1/OUT0	OUT0:PWMOUT0	—	
B1	P1.2/SCL	—	I <sup>2</sup> C Clock	
A1	P1.3/SDA	—	I <sup>2</sup> C Data	
A2	P1.6/OVF0/UND0/nO UT0/CMPO_0	nOUT0:Complement of OUT0, UND0, OVF0	CMPO_0: Sense Comp Out, Internal Reset function <sup>[3]</sup>	
B2	P1.7/MATCH/ EXT_CLK	MATCH: Match Out	External Clock	
A3	P2.0	—	—	
B3	P3.0/SDA/SWD_IO	—	I <sup>2</sup> C Data, SWD I/O	
A4	P3.1/SCL/SWD_CLK	—	I <sup>2</sup> C Clock, SWD Clock	

**Note**

3. Must not have load to ground during POR (should be an output).

## Power

The following power system diagrams (Figure 9 and Figure 10) show the set of power supply pins as implemented for the PSoC 4000. The system has one regulator in Active mode for the digital circuitry. There is no analog regulator; the analog circuits run directly from the  $V_{DD}$  input. There is a separate regulator for the Deep Sleep mode. The supply voltage range is either 1.8 V  $\pm 5\%$  (externally regulated) or 1.8 V to 5.5 V (unregulated externally; regulated internally) with all functions and circuits operating over that range.

The  $V_{DDIO}$  pin, available in the 16-pin QFN package, provides a separate voltage domain for the following pins: P3.0, P3.1, and P3.2. P3.0 and P3.1 can be I<sup>2</sup>C pins and the chip can thus communicate with an I<sup>2</sup>C system, running at a different voltage (where  $V_{DDIO} \leq V_{DD}$ ). For example,  $V_{DD}$  can be 3.3 V and  $V_{DDIO}$  can be 1.8 V.

The PSoC 4000 family allows two distinct modes of power supply operation: Unregulated External Supply and Regulated External Supply.

### Unregulated External Supply

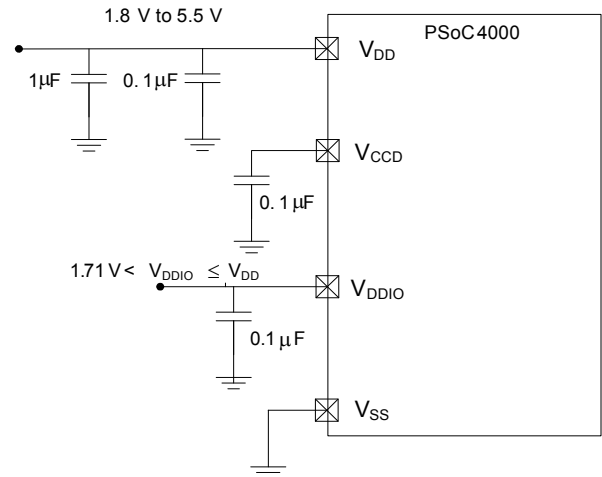
In this mode, the PSoC 4000 is powered by an external power supply that can be anywhere in the range of 1.8 to 5.5 V. This range is also designed for battery-powered operation. For example, the chip can be powered from a battery system that starts at 3.5 V and works down to 1.8 V. In this mode, the internal regulator of the PSoC 4000 supplies the internal logic and the  $V_{CCD}$  output of the PSoC 4000 must be bypassed to ground via an external capacitor (0.1  $\mu$ F; X5R ceramic or better).

Bypass capacitors must be used from  $V_{DD}$  to ground. The typical practice for systems in this frequency range is to use a capacitor in the 1- $\mu$ F range, in parallel with a smaller capacitor (0.1  $\mu$ F, for example). Note that these are simply rules of thumb and that, for critical applications, the PCB layout, lead inductance, and the bypass capacitor parasitic should be simulated to design and obtain optimal bypassing.

An example of a bypass scheme follows ( $V_{DDIO}$  is available on the 16-QFN package).

**Figure 9. 16-pin QFN Bypass Scheme Example - Unregulated External Supply**

Power supply connections when  $1.8 \leq V_{DD} \leq 5.5$  V



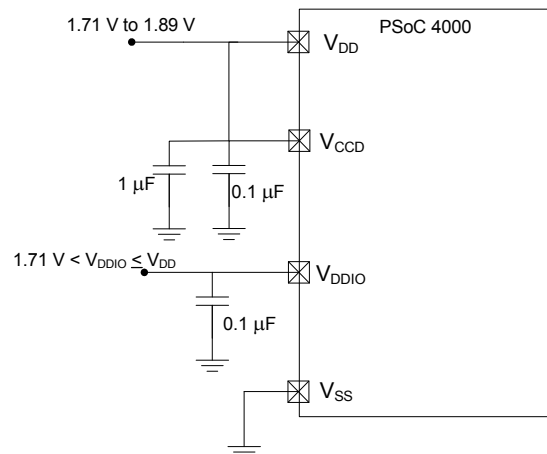
### Regulated External Supply

In this mode, the PSoC 4000 is powered by an external power supply that must be within the range of 1.71 to 1.89 V; note that this range needs to include the power supply ripple too. In this mode, the  $V_{DD}$  and  $V_{CCD}$  pins are shorted together and bypassed. The internal regulator should be disabled in the firmware. Note that in this mode  $V_{DD}$  ( $V_{CCD}$ ) should never exceed 1.89 in any condition, including flash programming.

An example of a bypass scheme follows ( $V_{DDIO}$  is available on the 16-QFN package).

**Figure 10. 16-pin QFN Bypass Scheme Example - Regulated External Supply**

Power supply connections when  $1.71 \leq V_{DD} \leq 1.89$  V





**Table 4. DC Specifications (continued)**

 Typical values measured at  $V_{DD} = 3.3 \text{ V}$  and  $25^\circ\text{C}$ .

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
<b>Deep Sleep Mode, <math>V_{DD} = 3.6</math> to <math>5.5 \text{ V}</math> (Regulator on)</b>							
SID34	$I_{DD29}$	I <sup>2</sup> C wakeup and WDT on	–	2.5	12	μA	
<b>Deep Sleep Mode, <math>V_{DD} = V_{CCD} = 1.71</math> to <math>1.89 \text{ V}</math> (Regulator bypassed)</b>							
SID37	$I_{DD32}$	I <sup>2</sup> C wakeup and WDT on	–	2.5	9.2	μA	
<b>XRES Current</b>							
SID307	$I_{DD\_XR}$	Supply current while XRES asserted	–	2	5	mA	

**Table 5. AC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID48	$F_{CPU}$	CPU frequency	DC	–	16	MHz	$1.71 \leq V_{DD} \leq 5.5$
SID49 <sup>[5]</sup>	$T_{SLEEP}$	Wakeup from Sleep mode	–	0	–	μs	
SID50 <sup>[5]</sup>	$T_{DEEPSLEEP}$	Wakeup from Deep Sleep mode	–	35	–	μs	

#### GPIO

**Table 6. GPIO DC Specifications (referenced to  $V_{DDIO}$  for 16-Pin QFN  $V_{DDIO}$  pins)**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID57	$V_{IH}$ <sup>[6]</sup>	Input voltage high threshold	$0.7 \times V_{DD}$	–	–	V	CMOS Input
SID58	$V_{IL}$	Input voltage low threshold	–	–	$0.3 \times V_{DD}$	V	CMOS Input
SID241	$V_{IH}$ <sup>[6]</sup>	LVTTL input, $V_{DD} < 2.7 \text{ V}$	$0.7 \times V_{DD}$	–	–	V	
SID242	$V_{IL}$	LVTTL input, $V_{DD} < 2.7 \text{ V}$	–	–	$0.3 \times V_{DD}$	V	
SID243	$V_{IH}$ <sup>[6]</sup>	LVTTL input, $V_{DD} \geq 2.7 \text{ V}$	2.0	–	–	V	
SID244	$V_{IL}$	LVTTL input, $V_{DD} \geq 2.7 \text{ V}$	–	–	0.8	V	
SID59	$V_{OH}$	Output voltage high level	$V_{DD} - 0.6$	–	–	V	$I_{OH} = 4 \text{ mA}$ at $3 \text{ V } V_{DD}$
SID60	$V_{OH}$	Output voltage high level	$V_{DD} - 0.5$	–	–	V	$I_{OH} = 1 \text{ mA}$ at $1.8 \text{ V } V_{DD}$
SID61	$V_{OL}$	Output voltage low level	–	–	0.6	V	$I_{OL} = 4 \text{ mA}$ at $1.8 \text{ V } V_{DD}$
SID62	$V_{OL}$	Output voltage low level	–	–	0.6	V	$I_{OL} = 10 \text{ mA}$ at $3 \text{ V } V_{DD}$
SID62A	$V_{OL}$	Output voltage low level	–	–	0.4	V	$I_{OL} = 3 \text{ mA}$ at $3 \text{ V } V_{DD}$
SID63	$R_{PULLUP}$	Pull-up resistor	3.5	5.6	8.5	kΩ	
SID64	$R_{PULLDOWN}$	Pull-down resistor	3.5	5.6	8.5	kΩ	
SID65	$I_{IL}$	Input leakage current (absolute value)	–	–	2	nA	$25^\circ\text{C}$ , $V_{DD} = 3.0 \text{ V}$
SID66	$C_{IN}$	Input capacitance	–	3	7	pF	

#### Notes

5. Guaranteed by characterization.
6.  $V_{IH}$  must not exceed  $V_{DD} + 0.2 \text{ V}$ .

**Table 6. GPIO DC Specifications (referenced to  $V_{DDIO}$  for 16-Pin QFN  $V_{DDIO}$  pins) (continued)**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID67 <sup>[7]</sup>	$V_{HYSTTL}$	Input hysteresis LVTTL	15	40	—	mV	$V_{DD} \geq 2.7$ V
SID68 <sup>[7]</sup>	$V_{HYSCMOS}$	Input hysteresis CMOS	$0.05 \times V_{DD}$	—	—	mV	$V_{DD} < 4.5$ V
SID68A <sup>[7]</sup>	$V_{HYSCMOS5V5}$	Input hysteresis CMOS	200	—	—	mV	$V_{DD} > 4.5$ V
SID69 <sup>[7]</sup>	$I_{DIODE}$	Current through protection diode to $V_{DD}/V_{SS}$	—	—	100	$\mu$ A	
SID69A <sup>[7]</sup>	$I_{TOT\_GPIO}$	Maximum total source or sink chip current	—	—	85	mA	

**Table 7. GPIO AC Specifications**

(Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID70	$T_{RISEF}$	Rise time in fast strong mode	2	—	12	ns	3.3 V $V_{DD}$ , Cload = 25 pF
SID71	$T_{FALLF}$	Fall time in fast strong mode	2	—	12	ns	3.3 V $V_{DD}$ , Cload = 25 pF
SID72	$T_{RISES}$	Rise time in slow strong mode	10	—	60	—	3.3 V $V_{DD}$ , Cload = 25 pF
SID73	$T_{FALLS}$	Fall time in slow strong mode	10	—	60	—	3.3 V $V_{DD}$ , Cload = 25 pF
SID74	$F_{GPIOUT1}$	GPIO $F_{OUT}$ ; 3.3 V $\leq V_{DD} \leq 5.5$ V. Fast strong mode.	—	—	16	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID75	$F_{GPIOUT2}$	GPIO $F_{OUT}$ ; 1.71 V $\leq V_{DD} \leq 3.3$ V. Fast strong mode.	—	—	16	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID76	$F_{GPIOUT3}$	GPIO $F_{OUT}$ ; 3.3 V $\leq V_{DD} \leq 5.5$ V. Slow strong mode.	—	—	7	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID245	$F_{GPIOUT4}$	GPIO $F_{OUT}$ ; 1.71 V $\leq V_{DD} \leq 3.3$ V. Slow strong mode.	—	—	3.5	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID246	$F_{GPIOIN}$	GPIO input operating frequency; 1.71 V $\leq V_{DD} \leq 5.5$ V	—	—	16	MHz	90/10% $V_{IO}$

**Note**

7. Guaranteed by characterization.

## XRES

**Table 8. XRES DC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID77	$V_{IH}$	Input voltage high threshold	$0.7 \times V_{DD}$	–	–	V	CMOS Input
SID78	$V_{IL}$	Input voltage low threshold	–	–	$0.3 \times V_{DD}$	V	CMOS Input
SID79	$R_{PULLUP}$	Pull-up resistor	3.5	5.6	8.5	k $\Omega$	
SID80	$C_{IN}$	Input capacitance	–	3	7	pF	
SID81 <sup>[8]</sup>	$V_{HYSXRES}$	Input voltage hysteresis	–	$0.05 \times V_{DD}$	–	mV	Typical hysteresis is 200 mV for $V_{DD} > 4.5V$

**Table 9. XRES AC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID83 <sup>[8]</sup>	$T_{RESETWIDTH}$	Reset pulse width	5	–	–	$\mu s$	
BID#194 <sup>[8]</sup>	$T_{RESETWAKE}$	Wake-up time from reset release	–	–	3	ms	

## Analog Peripherals

### Comparator

**Table 10. Comparator DC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID330 <sup>[8]</sup>	$I_{CMP1}$	Block current, High Bandwidth mode	–	–	110	$\mu A$	
SID331 <sup>[8]</sup>	$I_{CMP2}$	Block current, Low Power mode	–	–	85	$\mu A$	
SID332 <sup>[8]</sup>	$V_{OFFSET1}$	Offset voltage, High Bandwidth mode	–	10	30	mV	
SID333 <sup>[8]</sup>	$V_{OFFSET2}$	Offset voltage, Low Power mode	–	10	30	mV	
SID334 <sup>[8]</sup>	$Z_{CMP}$	DC input impedance of comparator	35	–	–	M $\Omega$	
SID338 <sup>[8]</sup>	VINP_COMP	Comparator input range	0	–	3.6	V	Max input voltage is lower of 3.6 V or $V_{DD}$
SID339	VREF_COMP	Comparator internal voltage reference	1.188	1.2	1.212	V	

**Note**

8. Guaranteed by characterization.

**Table 11. Comparator AC Specifications (Guaranteed by Characterization)**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID336 <sup>[8]</sup>	T <sub>COMP1</sub>	Response Time High Bandwidth mode, 50-mV overdrive	–	–	90	ns	
SID337 <sup>[8]</sup>	T <sub>COMP2</sub>	Response Time Low Power mode, 50-mV overdrive	–	–	110	ns	

### CSD

**Table 12. CSD and IDAC Block Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
<b>CSD and IDAC Specifications</b>							
SYS.PER#3	VDD_RIPPLE	Max allowed ripple on power supply, DC to 10 MHz	–	–	±50	mV	VDD > 2V (with ripple), 25 °C T <sub>A</sub> , Sensitivity = 0.1 pF
SYS.PER#16	VDD_RIPPLE_1.8	Max allowed ripple on power supply, DC to 10 MHz	–	–	±25	mV	VDD > 1.75V (with ripple), 25 °C T <sub>A</sub> , Parasitic Capacitance (C <sub>P</sub> ) < 20 pF, Sensitivity ≥ 0.4 pF
SID.CSD#15	VREFHI	Reference Buffer Output	1.1	1.2	1.3	V	
SID.CSD#16	IDAC1IDD	IDAC1 (8-bits) block current	–	–	1125	µA	
SID.CSD#17	IDAC2IDD	IDAC2 (7-bits) block current	–	–	1125	µA	
SID308	V <sub>CSD</sub>	Voltage range of operation	1.71	–	5.5	V	1.8 V ±5% or 1.8 V to 5.5 V
SID308A	VCOMPIDAC	Voltage compliance range of IDAC	0.8	–	V <sub>DD</sub> – 0.8	V	
SID309	IDAC1 <sub>DNL</sub>	DNL for 8-bit resolution	–1	–	1	LSB	
SID310	IDAC1 <sub>INL</sub>	INL for 8-bit resolution	–3	–	3	LSB	
SID311	IDAC2 <sub>DNL</sub>	DNL for 7-bit resolution	–1	–	1	LSB	
SID312	IDAC2 <sub>INL</sub>	INL for 7-bit resolution	–3	–	3	LSB	
SID313	SNR	Ratio of counts of finger to noise. Guaranteed by characterization	5	–	–	Ratio	Capacitance range of 9 to 35 pF, 0.1 pF sensitivity
SID314	IDAC1 <sub>CRT1</sub>	Output current of IDAC1 (8 bits) in high range	–	612	–	µA	
SID314A	IDAC1 <sub>CRT2</sub>	Output current of IDAC1(8 bits) in low range	–	306	–	µA	
SID315	IDAC2 <sub>CRT1</sub>	Output current of IDAC2 (7 bits) in high range	–	304.8	–	µA	
SID315A	IDAC2 <sub>CRT2</sub>	Output current of IDAC2 (7 bits) in low range	–	152.4	–	µA	
SID320	IDAC <sub>OFFSET</sub>	All zeroes input	–	–	±1	LSB	
SID321	IDAC <sub>GAIN</sub>	Full-scale error less offset	–	–	±10	%	
SID322	IDAC <sub>MISMATCH</sub>	Mismatch between IDACs	–	–	7	LSB	
SID323	IDAC <sub>SET8</sub>	Settling time to 0.5 LSB for 8-bit IDAC	–	–	10	µs	Full-scale transition. No external load.
SID324	IDAC <sub>SET7</sub>	Settling time to 0.5 LSB for 7-bit IDAC	–	–	10	µs	Full-scale transition. No external load.
SID325	CMOD	External modulator capacitor.	–	2.2	–	nF	5-V rating, X7R or NP0 cap.

**Table 25. External Clock Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID305 <sup>[14]</sup>	ExtClkFreq	External clock input frequency	0	–	16	MHz	
SID306 <sup>[14]</sup>	ExtClkDuty	Duty cycle; measured at $V_{DD}/2$	45	–	55	%	

**Table 26. Block Specs**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID262 <sup>[14]</sup>	T <sub>CLKSWITCH</sub>	System clock source switching time	3	–	4	Periods	

**Note**

14. Guaranteed by characterization.



The Field Values are listed in the following table:

Field	Description	Values	Meaning
CY8C	Cypress prefix		
4	Architecture	4	PSoC 4
A	Family	0	4000 Family
B	CPU speed	1	16 MHz
		4	48 MHz
C	Flash capacity	3	8 KB
		4	16 KB
		5	32 KB
		6	64 KB
		7	128 KB
DE	Package code	SX	SOIC
		LQ	QFN
		PV	SSOP
		FN	WLCSP
F	Temperature range	I	Industrial
XYZ	Attributes code	000-999	Code of feature set in specific family

## Packaging

**Table 27. Package List**

Spec ID#	Package	Description
BID#47A	28-Pin SSOP	28-pin 5 × 10 × 1.65mm SSOP with 0.65-mm pitch
BID#26	24-Pin QFN	24-pin 4 × 4 × 0.6 mm QFN with 0.5-mm pitch
BID#33	16-Pin QFN	16-pin 3 × 3 × 0.6 mm QFN with 0.5-mm pitch
BID#40	16-Pin SOIC	16-pin (150 Mil) SOIC
BID#47	8-Pin SOIC	8-pin (150 Mil) SOIC
BID#147A	16-Ball WLCSP	16-Ball 1.47 × 1.58 × 0.4 mm

**Table 28. Package Characteristics**

Parameter	Description	Conditions	Min	Typ	Max	Units
T <sub>A</sub>	Operating ambient temperature		−40	25	85	°C
T <sub>J</sub>	Operating junction temperature		−40	–	100	°C
T <sub>JA</sub>	Package θ <sub>JA</sub> (28-pin SSOP)		–	66.6	–	°C/Watt
T <sub>JC</sub>	Package θ <sub>JC</sub> (28-pin SSOP)		–	34	–	°C/Watt
T <sub>JA</sub>	Package θ <sub>JA</sub> (24-pin QFN)		–	38	–	°C/Watt
T <sub>JC</sub>	Package θ <sub>JC</sub> (24-pin QFN)		–	5.6	–	°C/Watt
T <sub>JA</sub>	Package θ <sub>JA</sub> (16-pin QFN)		–	49.6	–	°C/Watt
T <sub>JC</sub>	Package θ <sub>JC</sub> (16-pin QFN)		–	5.9	–	°C/Watt
T <sub>JA</sub>	Package θ <sub>JA</sub> (16-pin SOIC)		–	142	–	°C/Watt
T <sub>JC</sub>	Package θ <sub>JC</sub> (16-pin SOIC)		–	49.8	–	°C/Watt
T <sub>JA</sub>	Package θ <sub>JA</sub> (16-ball WLCSP)		–	90	–	°C/Watt
T <sub>JC</sub>	Package θ <sub>JC</sub> (16-ball WLCSP)		–	0.9	–	°C/Watt
T <sub>JA</sub>	Package θ <sub>JA</sub> (8-pin SOIC)		–	198	–	°C/Watt
T <sub>JC</sub>	Package θ <sub>JC</sub> (8-pin SOIC)		–	56.9	–	°C/Watt

**Table 29. Solder Reflow Peak Temperature**

Package	Maximum Peak Temperature	Maximum Time at Peak Temperature
All	260 °C	30 seconds

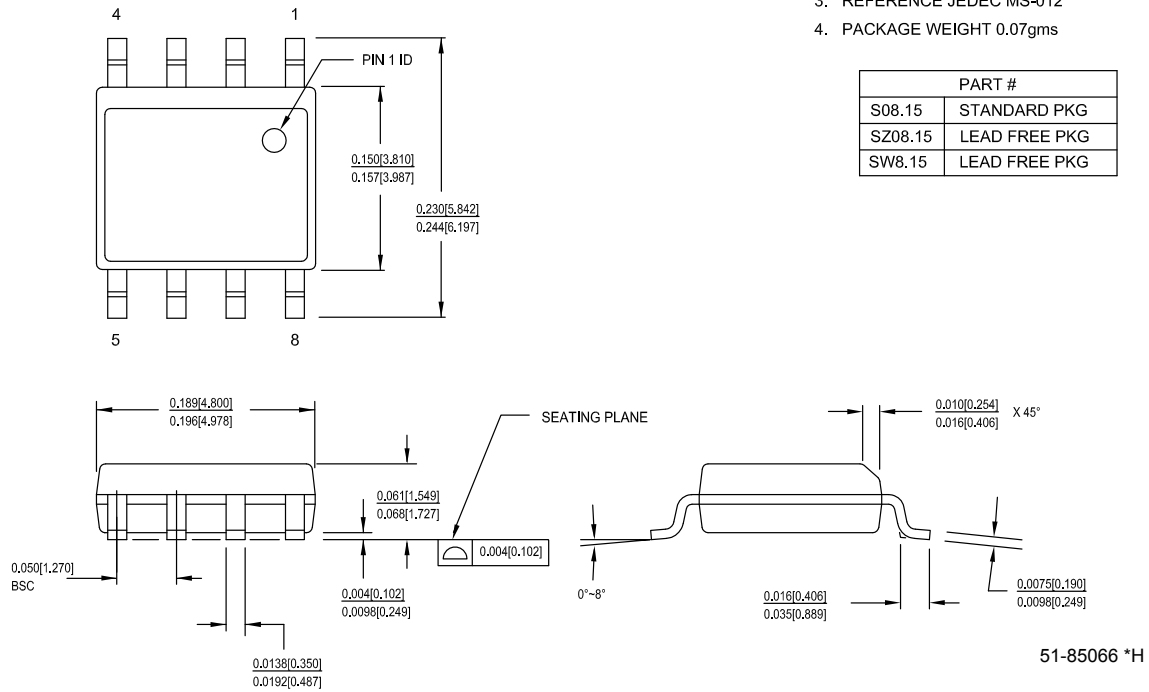
**Table 30. Package Moisture Sensitivity Level (MSL), IPC/JEDEC J-STD-020**

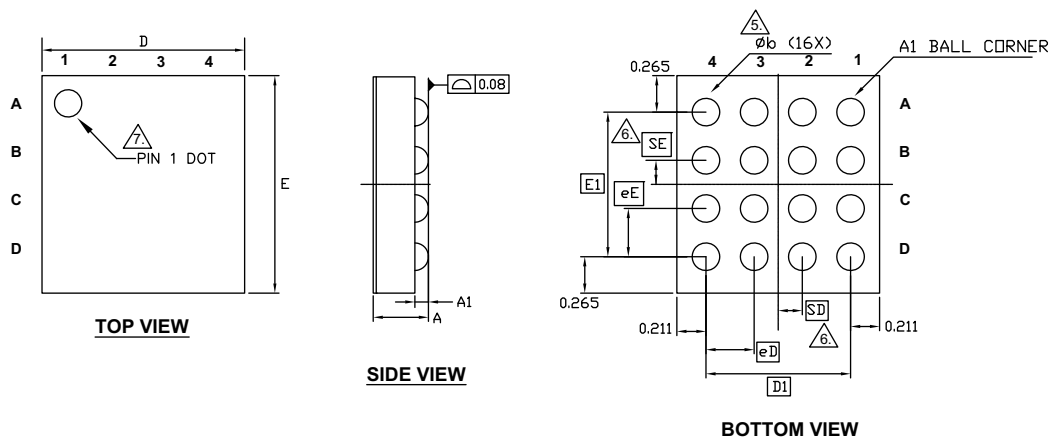
Package	MSL
All except WLCSP	MSL 3
16-ball WLCSP	MSL 1



**Figure 15. 8-pin (150-mil) SOIC Package Outline**

1. DIMENSIONS IN INCHES[MM] MIN.  
MAX.
2. PIN 1 ID IS OPTIONAL.  
ROUND ON SINGLE LEADFRAME  
RECTANGULAR ON MATRIX LEADFRAME
3. REFERENCE JEDEC MS-012
4. PACKAGE WEIGHT 0.07gms



**Figure 16. 16-Ball WLCSP 1.47 x 1.58 x 0.4 mm**


SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	-	-	0.42
A1	0.089	0.099	0.109
D	1.447	1.472	1.497
E	1.554	1.579	1.604
D1	1.05 BSC		
E1	1.05 BSC		
MD	4		
ME	4		
N	16		
Ø b	0.17	0.20	0.23
eD	0.35 BSC		
eE	0.35 BSC		
SD	0.18 BSC		
SE	0.18 BSC		

**NOTES:**

- ALL DIMENSIONS ARE IN MILLIMETERS.
- SOLDER BALL POSITION DESIGNATION PER JEP95, SECTION 3, SPP-020.
- "e" REPRESENTS THE SOLDER BALL GRID PITCH.
- SYMBOL "MD" IS THE BALL MATRIX SIZE IN THE "D" DIRECTION. SYMBOL "ME" IS THE BALL MATRIX SIZE IN THE "E" DIRECTION. N IS THE NUMBER OF POPULATED SOLDER BALL POSITIONS FOR MATRIX SIZE MD X ME.
- DIMENSION "b" IS MEASURED AT THE MAXIMUM BALL DIAMETER IN A PLANE PARALLEL TO DATUM C.
- "SD" AND "SE" ARE MEASURED WITH RESPECT TO DATUMS A AND B AND DEFINE THE POSITION OF THE CENTER SOLDER BALL IN THE OUTER ROW. WHEN THERE IS AN ODD NUMBER OF SOLDER BALLS IN THE OUTER ROW, "SD" OR "SE" = 0. WHEN THERE IS AN EVEN NUMBER OF SOLDER BALLS IN THE OUTER ROW, "SD" = eD/2 AND "SE" = eE/2.
- A1 CORNER TO BE IDENTIFIED BY CHAMFER, LASER OR INK MARK METALIZED MARK, INDENTATION OR OTHER MEANS.
- "+" INDICATES THE THEORETICAL CENTER OF DEPOPULATED SOLDER BALLS.
- JEDEC SPECIFICATION NO. REF. : N/A.

002-18598 \*\*

**Table 31. Acronyms Used in this Document** *(continued)*

Acronym	Description
PC	program counter
PCB	printed circuit board
PGA	programmable gain amplifier
PHUB	peripheral hub
PHY	physical layer
PICU	port interrupt control unit
PLA	programmable logic array
PLD	programmable logic device, see also PAL
PLL	phase-locked loop
PMDD	package material declaration data sheet
POR	power-on reset
PRES	precise power-on reset
PRS	pseudo random sequence
PS	port read data register
PSoC®	Programmable System-on-Chip™
PSRR	power supply rejection ratio
PWM	pulse-width modulator
RAM	random-access memory
RISC	reduced-instruction-set computing
RMS	root-mean-square
RTC	real-time clock
RTL	register transfer language
RTR	remote transmission request
RX	receive
SAR	successive approximation register
SC/CT	switched capacitor/continuous time
SCL	I <sup>2</sup> C serial clock
SDA	I <sup>2</sup> C serial data
S/H	sample and hold
SINAD	signal to noise and distortion ratio
SIO	special input/output, GPIO with advanced features. See GPIO.
SOC	start of conversion
SOF	start of frame
SPI	Serial Peripheral Interface, a communications protocol
SR	slew rate
SRAM	static random access memory
SRES	software reset
SWD	serial wire debug, a test protocol

**Table 31. Acronyms Used in this Document** *(continued)*

Acronym	Description
SWV	single-wire viewer
TD	transaction descriptor, see also DMA
THD	total harmonic distortion
TIA	transimpedance amplifier
TRM	technical reference manual
TTL	transistor-transistor logic
TX	transmit
UART	Universal Asynchronous Transmitter Receiver, a communications protocol
UDB	universal digital block
USB	Universal Serial Bus
USBIO	USB input/output, PSoC pins used to connect to a USB port
VDAC	voltage DAC, see also DAC, IDAC
WDT	watchdog timer
WOL	write once latch, see also NVL
WRES	watchdog timer reset
XRES	external reset I/O pin
XTAL	crystal

## Revision History

Description Title: PSoC <sup>®</sup> 4: PSoC 4000 Family Datasheet Programmable System-on-Chip (PSoC <sup>®</sup> ) Document Number: 001-89638				
Revision	ECN	Orig. of Change	Submission Date	Description of Change
*B	4348760	WKA	05/16/2014	New PSoC 4000 datasheet.
*C	4514139	WKA	10/27/2014	Added 28-pin SSOP pin and package details. Updated $V_{REF}$ spec values. Updated conditions for SID174. Updated SID.CSD#15 values and description. Added spec SID339.
*D	4617283	WKA	01/09/2015	Corrected Development Kits information and PSoC Creator Example Project figure. Corrected typo in the ordering information table. Updated 28-pin SSOP package diagram.
*E	4735762	WKA	05/26/2015	Added 16-ball WLCSP pin and package details.
*F	5466193	WKA	10/07/2016	Updated <a href="#">Table 30</a> . Updated 8-pin SOIC package diagram. Updated the template.
*G	5685079	TSEN	04/05/2017	Updated 16-ball WLCSP package details.

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